

## DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claim and for which a patent is sought on the invention entitled:

**"Integrated Circuit Package With Multiple Heat Dissipation Paths"**

the specification of which: (check one)

☒ [X] is attached hereto ☐ [ ] was filed on \_\_\_\_\_, as United States Patent Application Serial No. \_\_\_\_\_, or PCT International Application Number \_\_\_\_\_, and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with 37 CFR § 1.56(a).

Prior Foreign Application(s): I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor certificate listed below, or § 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)			PRIORITY CLAIMED	
Number	Country	Day/Month/Year Filed	Yes	No
88209607	Taiwan R.O.C.	11/6/1999	X	

I hereby Claim the benefit under Title 35, United States Code § 119(e) of any United States provisional application(s) listed below:

Application No.	Filing Date

I hereby claim the benefit under 35 U.S.C § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by 35 U.S.C. § 112, first paragraph, I acknowledge the duty to disclose material information as defined in 37 CFR § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:


Application Serial No.	U.S. Filing Date	Status - Patented, Pending, Abandoned

I hereby appoint Elliott I. Pollock, Registration No. 16,906; George Vande Sande, Registration No. 17,276; Robert R. Priddy, Registration No. 20,169; Burton A. Amernick, Registration No. 24,852; Stanley B. Green, Registration No. 24,351; Richard Wiener, Registration No. 18,741; Townsend M. Belser, Jr., Registration No. 22,956; Morris Liss, Registration No. 24,510; Martin Abramson, Registration No. 25,787; George R. Pettit, Registration No. 27,369; Elzbieta Chlopecka, Registration No. 32,767; Eric J. Franklin, Registration No. 37,134; and Jeffri A. Kaminski, Registration No. P-42,709, my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Send Correspondence and Direct Telephone Calls to:  
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor <b>Po-Yao Lin</b>	Citizenship <b>Taiwan, R.O.C.</b>
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Date <b>18 Aug. 1999</b>	Signature 

[ X ] See Next Page For additional inventors

## Declaration For Patent Application

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Full name of second joint inventor (if any) <b>Ching-Bai Hwang</b>	Citizenship <b>Taiwan, R.O.C.</b>
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Date <i>18 Aug. 1999</i>	Signature <i>Hwang, Ching-Bai</i>

Full name of third joint inventor (if any)	Citizenship
Residence Address	Post Office Address [x] Same as Residence
Date	Signature

Full name of forth joint inventor (if any)	Citizenship
Residence Address	Post Office Address [x] Same as Residence
Date	Signature

Full name of fifth joint inventor (if any)	Citizenship
Residence Address	Post Office Address [x] Same as Residence
Date	Signature